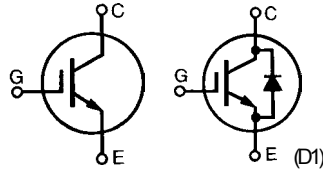


HiPerFAST™ IGBT

IXGH39N60B
IXGH39N60BD1
IXGT39N60B
IXGT39N60BD1

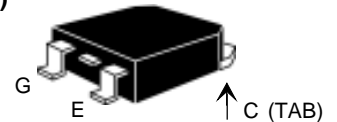
$V_{CES} = 600 \text{ V}$
 $I_{C25} = 76 \text{ A}$
 $V_{CE(sat)} = 1.7 \text{ V}$
 $t_{fi} = 200 \text{ ns}$

Preliminary data

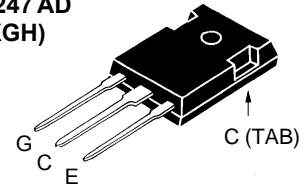


Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	600	V
V_{CGR}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}; R_{GE} = 1 \text{ M}\Omega$	600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ\text{C}$	76	A
I_{C90}	$T_C = 90^\circ\text{C}$	39	A
I_{CM}	$T_C = 25^\circ\text{C}, 1 \text{ ms}$	152	A
SSOA (RBSOA)	$V_{GE} = 15 \text{ V}, T_{VJ} = 125^\circ\text{C}, R_G = 22 \Omega$ Clamped inductive load	$I_{CM} = 76$ @ $0.8 V_{CES}$	A
P_C	$T_C = 25^\circ\text{C}$	200	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$
M_d	Mounting torque (M3) TO-247	1.13/10Nm/lb.in.	
Weight		TO-247 AD	6 g
		TO-268	4 g

TO-268 (IXGT)



TO-247 AD (IXGH)



G = Gate, C = Collector,
E = Emitter, TAB = Collector

Features

- International standard packages JEDEC TO-247 AD & TO-268
- High current handling capability
- Newest generation HDMOS™ process
- MOS Gate turn-on - drive simplicity

Applications

- PFC circuits
- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies

Advantages

- High power density
- Very fast switching speeds for high frequency applications

Symbol	Test Conditions		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
			Min.	Typ.	Max.
BV_{CES}	$I_C = 250 \mu\text{A}, V_{GE} = 0 \text{ V}$	39N60B	600		V
		39N60BD1	600		
$V_{GE(th)}$	$I_C = 250 \mu\text{A}, V_{CE} = V_{GE}$	39N60B	2.5		5.0 V
		39N60BD1	2.5		5.0 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}, V_{GE} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ 39N60B			200 μA
		$T_J = 125^\circ\text{C}$ 39N60B			1 mA
		$T_J = 125^\circ\text{C}$ 39N60BD1			3 mA
I_{GES}	$V_{CE} = 0 \text{ V}, V_{GE} = \pm 20 \text{ V}$				$\pm 100 \text{ nA}$
$V_{CE(sat)}$	$I_C = I_{90}, V_{GE} = 15 \text{ V}$				1.7 V

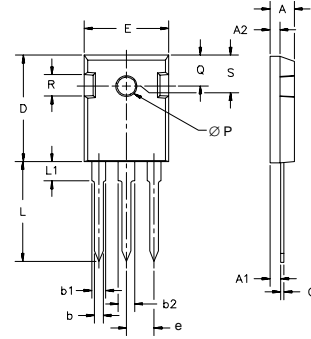
Symbol	Test Conditions	Characteristic Values		
		(T _J = 25°C, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	I _C = I _{C90} ; V _{CE} = 10 V, Pulse test, t ≤ 300 μs, duty cycle ≤ 2 %	19	28	S
C_{ies}	V _{CE} = 25 V, V _{GE} = 0 V, f = 1 MHz		2750	pF
C_{oes}		39N60B	200	pF
C_{res}		39N60BD1	240	pF
Q_G	I _C = I _{C90} , V _{GE} = 15 V, V _{CE} = 0.5 V _{CES}		110	150 nC
Q_{GE}		25	35 nC	
Q_{GC}		40	75 nC	
t_{d(on)}	Inductive load, T_J = 25°C		25	ns
t_{ri}	I _C = I _{C90} , V _{GE} = 15 V		30	ns
t_{d(off)}	V _{CE} = 0.8 V _{CES} , R _G = R _{off} = 4.7 Ω		250	500 ns
t_{fi}	Remarks: Switching times may increase for V _{CE} (Clamp) > 0.8 • V _{CES} ,		200	360 ns
E_{off}	higher T _J or increased R _G		4.0	6.0 mJ
t_{d(on)}	Inductive load, T_J = 125°C		25	ns
t_{ri}	I _C = I _{C90} , V _{GE} = 15 V		30	ns
E_{on}	V _{CE} = 0.8 V _{CES} , R _G = R _{off} = 4.7 Ω		0.3	mJ
t_{d(off)}	Remarks: Switching times may increase for V _{CE} (Clamp) > 0.8 • V _{CES} ,		360	ns
t_{fi}	higher T _J or increased R _G		350	ns
E_{off}			6.0	mJ
R_{thJC}				0.62 K/W
R_{thCK}			0.25	K/W

Reverse Diode (FRED)

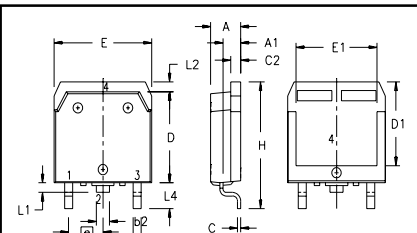
Characteristic Values
(T_J = 25°C, unless otherwise specified)

Symbol	Test Conditions	Characteristic Values		
		min.	typ.	max.
V_F	I _F = I _{C90} ; V _{GE} = 0 V, Pulse test t ≤ 300 μs, duty cycle d ≤ 2 %	T _J = 150°C		1.6 V
		T _J = 25°C		2.5 V
I_{RM}	I _F = I _{C90} ; V _{GE} = 0 V, -di _F /dt = 100 A/μs		6	A
t_{rr}		V _R = 100 V	T _J = 100°C	100 ns
		I _F = 1 A; -di _F /dt = 100 A/μs; V _R = 30 V	T _J = 25°C	25 ns
R_{thJC}				0.9 K/W

TO-247 AD Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A ₁	.106	.114	2.70	2.90
A ₂	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b ₂	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C ₂	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D ₁	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E ₁	.524	.535	13.30	13.60
e		.215 BSC		5.45 BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L ₁	.047	.055	1.20	1.40
L ₂	.039	.045	1.00	1.15
L ₃	.010	BSC	0.25	BSC
L ₄	.150	.161	3.80	4.10

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETS and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,881,106	5,017,508	5,049,961	5,187,117	5,486,715	6,306,728B1
4,850,072	4,931,844	5,034,796	5,063,307	5,237,481	5,381,025	

Fig. 1. Saturation Voltage Characteristics @ 25 Deg. C

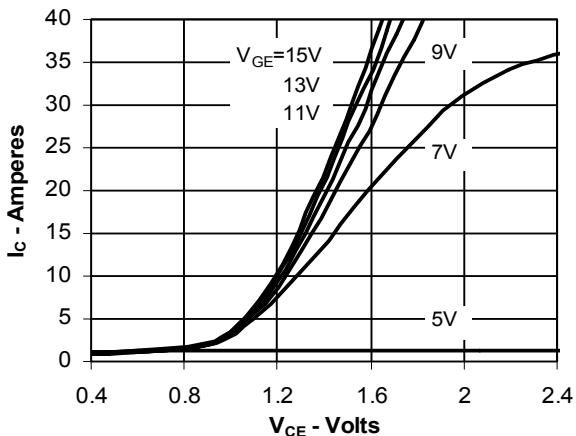


Fig. 2. Extended Output Characteristics @ 25 Deg. C

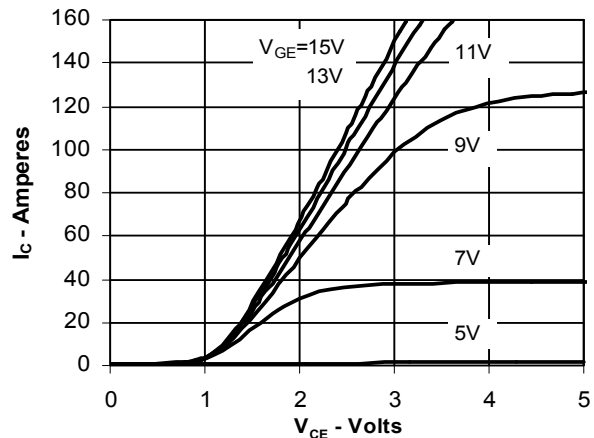


Fig. 3. Saturation Voltage Characteristics @ 125 Deg. C

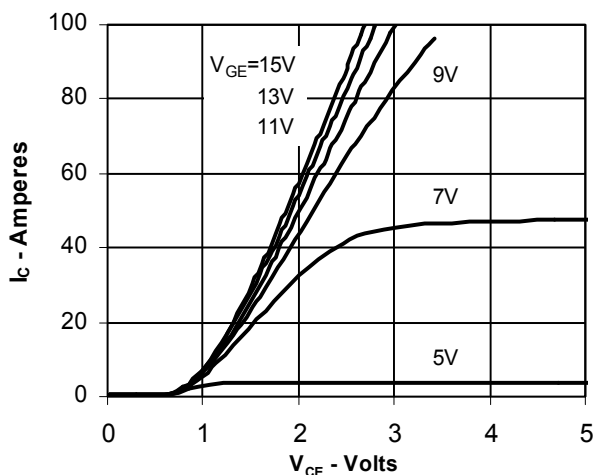


Fig. 4. Temperature Dependence of $V_{CE(SAT)}$

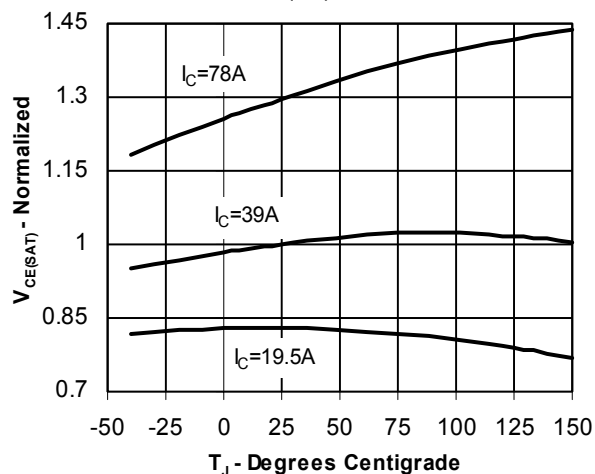


Fig. 5. BV_{CES} & $V_{(GE)TH}$ vs. Junction Temperature

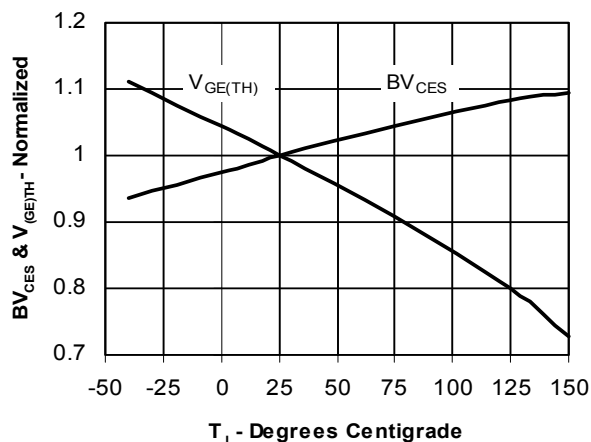


Fig. 6. Admittance

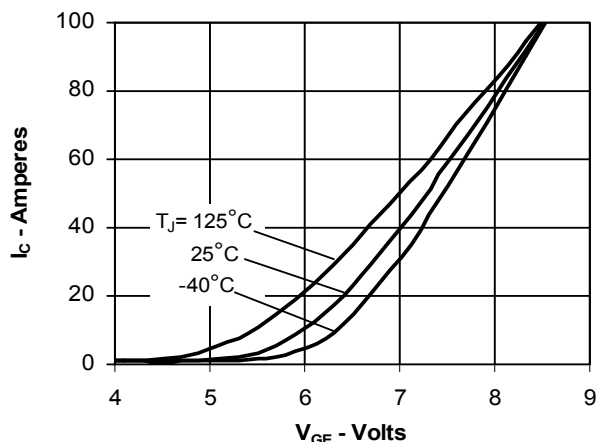


Fig. 7. Transconductance

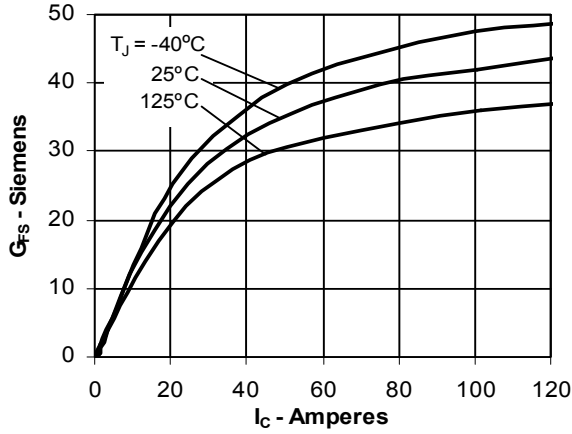


Fig. 8. Dependence of E_{OFF} on I_c

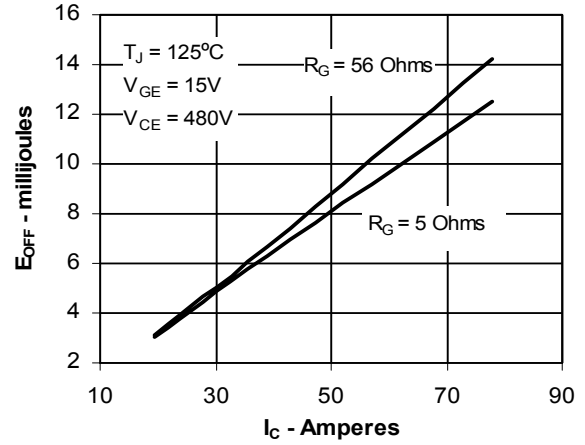


Fig. 9. Dependence of E_{OFF} on R_G

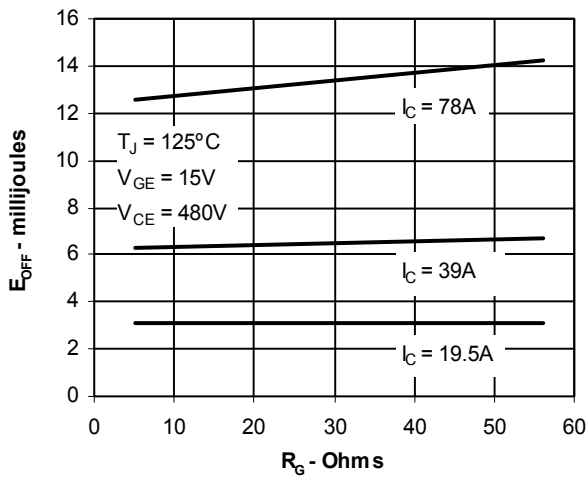


Fig. 10. Dependence of E_{OFF} on Temperature

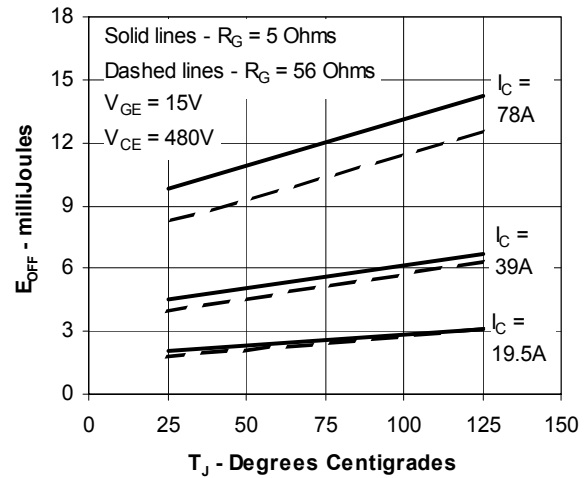


Fig. 11. Gate Charge

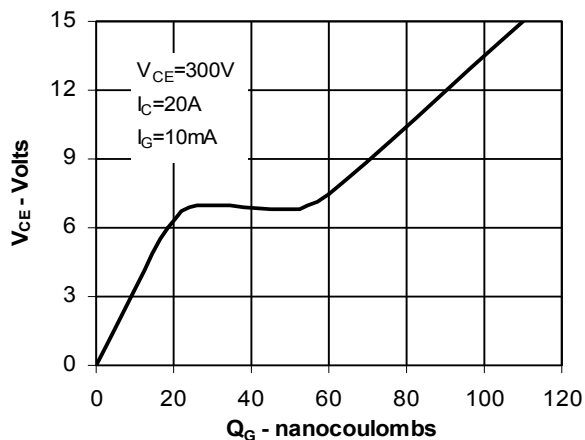
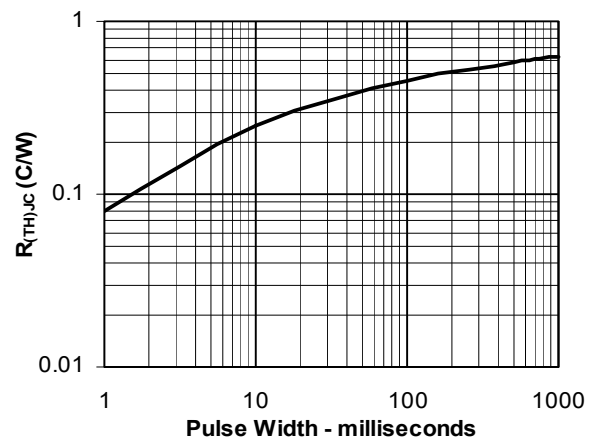


Fig. 12. Transient Thermal Response



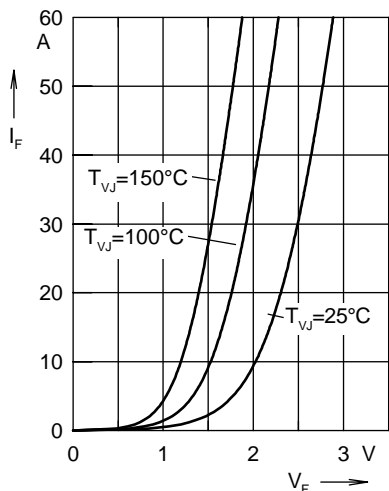


Fig. 12 Forward current I_F versus V_F

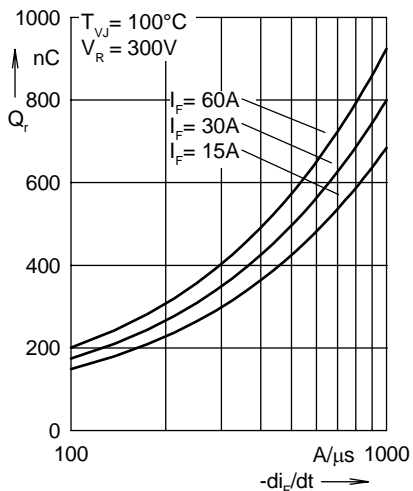


Fig. 13 Reverse recovery charge Q_r versus $-di_F/dt$

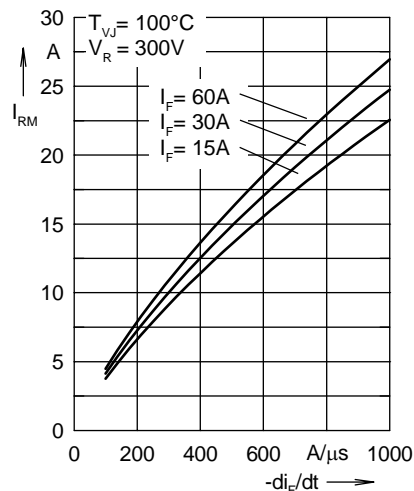


Fig. 14 Peak reverse current I_{RM} versus $-di_F/dt$

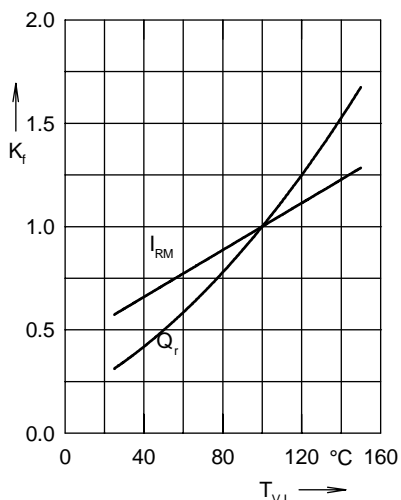


Fig. 15 Dynamic parameters Q_r, I_{RM} versus T_{VJ}

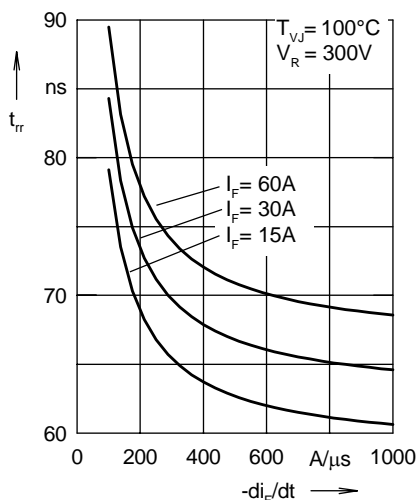


Fig. 16 Recovery time t_{rr} versus $-di_F/dt$

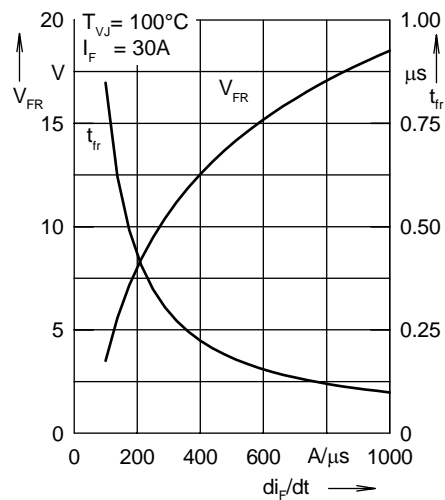


Fig. 17 Peak forward voltage V_{FR} and t_{rr} versus di_F/dt

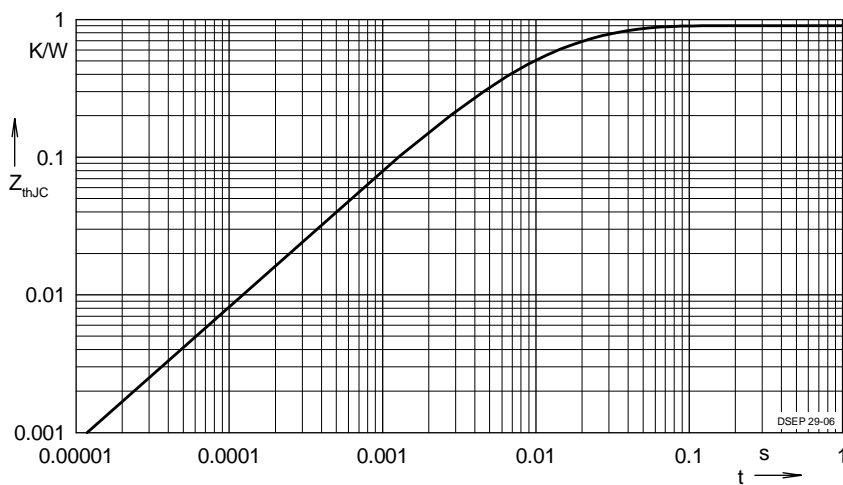


Fig. 18 Transient thermal resistance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.502	0.0052
2	0.193	0.0003
3	0.205	0.0162